

Atty Docket No.: JCLA7793-R

Serial No.: 10/047,681

IN THE CLAIMS

Please amend the claims as follows.

Claim 1. (re-presented – formerly independent claim 1) A bonded anisotropic conductive film, comprising:

a resin material; and

a plurality of conductive particles dispersed in the resin material, wherein one or more conductive particle includes a solder material covered with an outermost flux layer.

2. (Original) The bonded anisotropic conductive film of claim 1, wherein ~~material forming the conductive bead~~ particles further include conductive beads encapsulated in the solder material includes gold.

3. (Currently Amended) The bonded anisotropic conductive film of claim 1, wherein the solder material ~~forming the bonding layer~~ includes lead-tin alloy.

4. (Currently Amended) A bonded anisotropic conductive film, comprising:

a plastic material; and

a plurality of conductive particles within the plastic material, wherein each conductive particle has a conductive bead, a bonding layer and an insulating layer, wherein the bonding layer

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is comprised of a ~~conductive material~~ lead-tin alloy and covers the surface of the conductive bead, and wherein the insulating layer forms an outermost covering layer of each of said conductive bead.

5. (Original) The bonded anisotropic conductive film of claim 4, wherein the plastic material includes a thermal set material.

6. (Original) The bonded anisotropic conductive film of claim 4, wherein material forming the conductive bead includes gold.

Claim 7 (canceled).

8. (Original) The bonded anisotropic conductive film of claim 4, wherein the plastic material hardens after being raised to a first temperature and the bonding layer melts at a second temperature such that the second temperature is higher than the first temperature.

9. (Currently Amended) A bonded anisotropic conductive film, comprising:
a plastic material; and

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a plurality of conductive particles within the plastic material, wherein each conductive particle has a bonding layer and an insulating layer, wherein the bonding layer is comprised of a conductive material lead-tin alloy and forms a spherical structure, and wherein the insulating layer forms an outermost covering of each of the conductive particle.

10. (Original) The bonded anisotropic conductive film of claim 9, wherein the plastic material includes a thermal set material.

11. (Original) The bonded anisotropic conductive film of claim 9, wherein the bonding layer includes a conductive bead.

12. (Original) The bonded anisotropic conductive film of claim 11, wherein material forming the conductive bead includes gold.

Claim 13 (canceled).

14. (Original) The bonded anisotropic conductive film of claim 9, wherein the plastic material hardens after being raised to a first temperature and the bonding layer melts at a second temperature such that the second temperature is higher than the first temperature.

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15. (Original) A flip chip package having a bonded anisotropic conductive film structure in any one of the claims from 4 to 8, comprising:

a silicon chip, a carrier and a bonded anisotropic conductive film, wherein the silicon chip has a plurality of first contact points thereon and the carrier has a plurality of contact points thereon that correspond in position to the first contact points, the bonded anisotropic conductive film is inserted between the silicon chip and the carrier such that each pair of corresponding first contact point and second contact point form a common metallic bond through the bonding layer of conductive particles within the bonded anisotropic conductive film.

16. (Original) The flip chip package of claim 15, wherein material forming the conductive bead includes gold.

Claim 17 (canceled).

18. (New) The bonded anisotropic conductive film of claim 1, wherein the resin material comprises a thermosetting resin.

19. (New) The bonded anisotropic conductive film of claim 2, wherein the conductive beads are comprised of gold.